

SYSTEM AND METHOD FOR BACK-SIDE CONTACT
FOR TRENCH SEMICONDUCTOR DEVICE CHARACTERIZATION

Abstract of the Disclosure

5 A method for forming a back-side contact for a vertical
trench device includes grinding a back-side of a semiconductor
substrate, milling a trench in the back-side of the
semiconductor substrate, wherein a vertical trench fill is
exposed, and depositing a conductive material, wherein the
10 conductive material shorts the vertical trench fill to a buried
plate. Grinding the back-side of the semiconductor substrate
further includes grinding a dimple beneath a portion of the
vertical trench device, wherein the trench is milled in the
bottom portion of the dimple.